

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SUNIL RAO GANTA PAPA RAO BALA	08/01/2018
RICHARD BARGERHUFF	08/01/2018
NABEEL FATHI	08/01/2018
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State/Country:	TEXAS
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16051337
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ATTORNEY DOCKET NUMBER:	90545446
NAME OF SUBMITTER:	TRACI THOMAS
SIGNATURE:	/Traci Thomas/
DATE SIGNED:	08/01/2018
Total Attachments: 6	
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Hewlett Packard Enterprise
3404 E. Harmony Road
Mail Stop 79
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 90545446

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each), for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to Hewlett Packard Enterprise Development LP, a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPED), and to its subsidiaries and affiliates, agree to assign and transfer and hereby assign and transfer to HPED, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Patent entitled:

FLEXIBLE HEAT TRANSFER MECHANISM CONFIGURATIONS

Filing Date: July 31, 2018 Application No.: 16/051,337

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent of any countries thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Patent.


I/we additionally authorize HPED to file applications in my/our name for Patent in any country, to be held and enjoyed by HPED, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Patent, to HPED, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPED, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPED, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPED;

AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPED, as assignee of the entire right, title and interest, any and all Patent for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

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IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):


Inventor's Signature

8/11/2018
Date

Sunil Rao Ganta Papa Rao Baia

First/Middle Name/Last Name

Inventor's Signature

Date

Richard Bargerhuff

First/Middle Name/Last Name

Hewlett Packard Enterprise
3404 E. Harmony Road
Mail Stop 79
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 90545446

ASSIGNMENT OF PATENT APPLICATION (cont.)

Inventor's Signature Date

Nabeel Fathi

First/Middle Name/Last Name

Inventor's Signature Date

First/Middle Name/Last Name

Inventor's Signature Date

First/Middle Name/Last Name

Inventor's Signature Date

First/Middle Name/Last Name

Inventor's Signature Date

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Inventor's Signature

Date

Sunil Rao Ganta Papa Rao Bala

First/Middle Name/Last Name

First/Middle Name/Last Name



Inventor's Signature

2018 AUG 01

Date

Richard Bargerhuff

First/Middle Name/Last Name

First/Middle Name/Last Name

Hewlett Packard Enterprise
3404 E. Harmony Road
Mail Stop 79
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 90545446

ASSIGNMENT OF PATENT APPLICATION (cont.)

Inventor's Signature Date

Nabeel Fathi

First/Middle Name/Last Name

Inventor's Signature Date

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Inventor's Signature

Date

Sunil Rao Ganta Papa Rao Bala

First/Middle Name/Last Name

Inventor's Signature

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Richard Bargerhuff

First/Middle Name/Last Name

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PATENT APPLICATION

RECORD ID: 90545446

ASSIGNMENT OF PATENT APPLICATION (cont.)



Inventor's Signature

8/1/2018

Date

Nabeel Fathi

First/Middle Name/Last Name

Inventor's Signature

Date

First/Middle Name/Last Name

Inventor's Signature

Date

First/Middle Name/Last Name

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